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## Customer Information Notification

2013060171

**Issue Date:** 02-Jul-2013  
**Effective Date:** 06-Jul-2013

Here's your personalized quality information concerning products from NXP.

For detailed information we invite you to [view this notification online](#)



# QUALITY

### Management Summary

This Notification is about the change of resin hardener of two (2) Henkel mold compounds used in NXP product packaging, due to discontinued supply of the resin hardener by original supplier.

### Change Category

Wafer Fab process	Assembly Process	Product Marking	Design
Wafer Fab materials	Assembly Materials	Electrical spec./Test coverage	Mechanical Specification
Wafer Fab location	Assembly Location	Test Location	Packing/Shipping/Labeling

## Change of resin hardener of two Henkel mold compounds used in NXP products

### Information Notification

This is to inform about a minor change in Henkel mold compounds used in NXP product packaging. Henkel announced a change of supply source for the resin hardeners, due to discontinued supply by original supplier. They will be replaced by another supplier, with materials of same composition and same functionality. The affected Henkel mold compound series are GR646 and KL1000-3AP. An extended characterization and qualification has been carried out with all results pass. There is no change in product reliability and functionality.

### Why do we issue this Information Notification

The NXP products on the attached list are affected by this change.

### Identification of Affected Products

Backwards traceable via assembly week-code in the marking on the products.

### Impact

no impact to the product's functionality anticipated.

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Existing inventory will be shipped until depleted

### Additional information

### Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of \$4.36 billion in 2012.

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